2117002W 供应商

Small Signal MOSFET

60 V, 340 mA, Single, N-Channel, SC-70

Features

- ESD Protected
- Low R_{DS(on)}
- Small Footprint Surface Mount Package
- This is a Pb–Free Device

Applications

- Low Side Load Switch
- Level Shift Circuits
- DC–DC Converter
- Portable Applications i.e. DSC, PDA, Cell Phone, etc.

MAXIMUM RATINGS (T_J = 25° C unless otherwise stated)

Rating	Symbol	Value	Unit
Drain-to-Source Voltage	V _{DSS}	60	V
Gate-to-Source Voltage	V _{GS}	±20	V
$\label{eq:target} \begin{array}{ c c } \hline \text{Drain Current (Note 1)} \\ \text{Steady State} & T_{\text{A}} = 25^{\circ}\text{C} \\ T_{\text{A}} = 85^{\circ}\text{C} \\ \hline t < 5 \text{ s} & T_{\text{A}} = 25^{\circ}\text{C} \\ T_{\text{A}} = 85^{\circ}\text{C} \end{array}$	ID	310 220 340 240	mA
Power Dissipation (Note 1) Steady State t < 5 s	P _D	280 330	mW
Pulsed Drain Current ($t_p = 10 \ \mu s$)	I _{DM}	1.4	А
Operating Junction and Storage Temperature Range	T _J , T _{STG}	–55 to +150	°C
Source Current (Body Diode)	۱ _S	250	mA
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)	TL	260	°C
Gate-Source ESD Rating (HBM, Method 3015)	ESD	900	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Мах	Unit
Junction-to-Ambient - Steady State (Note 1)	$R_{ hetaJA}$	450	°C/W
Junction-to-Ambient - t ≤ 5 s (Note 1)	R _{0JA}	375	

1. Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces)

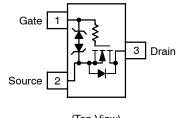


ON Semiconductor®

http://onsemi.com

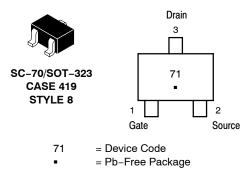
V _{(BR)DSS}	R _{DS(on)} MAX	I <mark>D MAX</mark> (Note 1)
60 V	1.6 Ω @ 10 V	340 mA
	2.5 Ω @ 4.5 V	

Simplified Schematic



(Top View)

MARKING DIAGRAM & PIN ASSIGNMENT



ORDERING INFORMATION

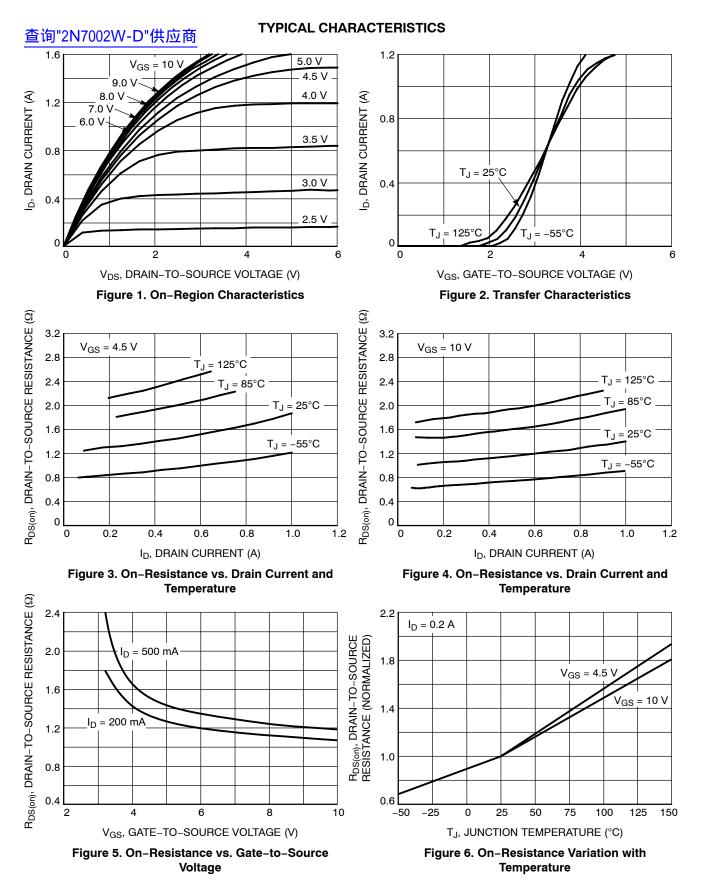
Device	Package	Shipping [†]
2N7002WT1G	SC–70 (Pb–Free)	3000/Tape & Reel

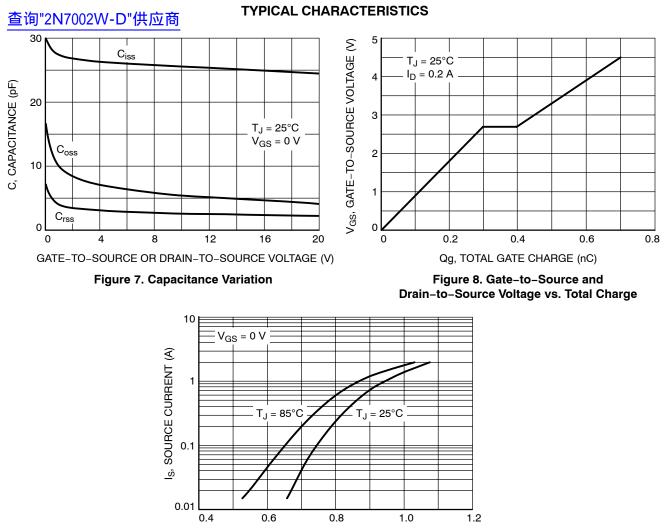
+ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ΈLECTRICAL/CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Units
OFF CHARACTERISTICS	-	•		-	-	-	-
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V_{GS} = 0 V, I_D = 250 μ A		60			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J				71		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V,	$T_J = 25^{\circ}C$			1	μΑ
		V _{DS} = 60 V	T _J = 125°C			500	μΑ
		V _{GS} = 0 V, V _{DS} = 50 V	T _J = 25°C			100	nA
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$				±10	μA
		V _{DS} = 0 V, V	/ _{GS} = ±10 V			450	nA
		V _{DS} = 0 V, V _{GS} = ±5.0 V				150	nA
ON CHARACTERISTICS (Note 2)		•		-			
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} ,	I _D = 250 μA	1.0		2.5	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J				4.0		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V_{GS} = 10 V, I _D = 500 mA			1.19	1.6	Ω
		V_{GS} = 4.5 V, I _D = 200 mA			1.33	2.5]
Forward Transconductance	9fs	V _{DS} = 5 V, I _D = 200 mA			80		S
CHARGES AND CAPACITANCES							
Input Capacitance	C _{ISS}				24.5		pF
Output Capacitance	C _{OSS}		f = 1 MHz, = 20 V		4.2]
Reverse Transfer Capacitance	C _{RSS}	•DS •	20 1		2.2		
Total Gate Charge	Q _{G(TOT)}				0.7		nC
Threshold Gate Charge	Q _{G(TH)}	V _{GS} = 4.5 V	, V _{DS} = 10 V;		0.1		
Gate-to-Source Charge	Q _{GS}		00 mA		0.3]
Gate-to-Drain Charge	Q _{GD}	1			0.1		
SWITCHING CHARACTERISTICS, V_{GS}	; = V (Note 3)						
Turn-On Delay Time	t _{d(ON)}	V _{GS} = 10 V, V _{DD} = 25 V, I _D = 500 mA, R _G = 25 Ω			12.2		ns
Rise Time	t _r				9.0		
Turn-Off Delay Time	t _{d(OFF)}				55.8		
Fall Time	t _f				29		
DRAIN-SOURCE DIODE CHARACTER	ISTICS						
Forward Diode Voltage	V _{SD}	V _{GS} = 0 V,	$T_J = 25^{\circ}C$		0.8	1.2	V
		I _S = 200 mA	T _J = 85°C		0.7		

2. Pulse Test: pulse width \leq 300 µs, duty cycle \leq 2% 3. Switching characteristics are independent of operating junction temperatures





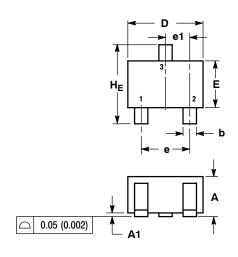
 V_{SD} , source-to-drain voltage (V)

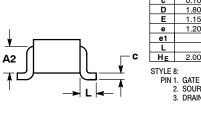
Figure 9. Diode Forward Voltage vs. Current

PACKAGE DIMENSIONS

SC-70 (SOT-323)

CASE 419-04 **ISSUE M**





NOTES

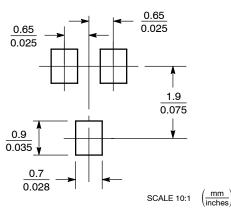
SOURCE

2. 3.

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.80	0.90	1.00	0.032	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A2	0.7 REF			0.028 REF		
b	0.30	0.35	0.40	0.012	0.014	0.016
c	0.10	0.18	0.25	0.004	0.007	0.010
D	1.80	2.10	2.20	0.071	0.083	0.087
Е	1.15	1.24	1.35	0.045	0.049	0.053
е	1.20	1.30	1.40	0.047	0.051	0.055
e1	0.65 BSC			0.026 BSC		
L	0.425 REF			0.017 REF		
HE	2.00	2.10	2.40	0.079	0.083	0.095

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and 💷 are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters, which may be provided in SCILC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILC does not convey any license under its patent rights or the rights of others. SCILC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Japan: ON Semiconductor, Japan Customer Focus Center 2-9-1 Kamimeguro, Meguro-ku, Tokyo, Japan 153-0051 Phone: 81-3-5773-3850

ON Semiconductor Website: http://onsemi.com

Order Literature: http://www.onsemi.com/litorder

For additional information, please contact your local Sales Representative.

查询"2N7002W-D"供应商